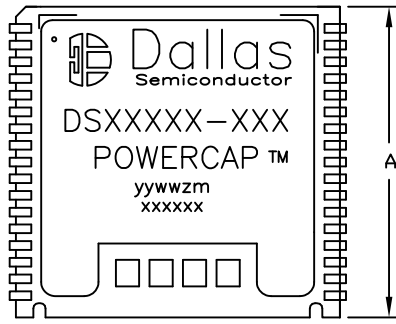
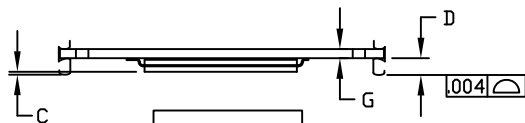


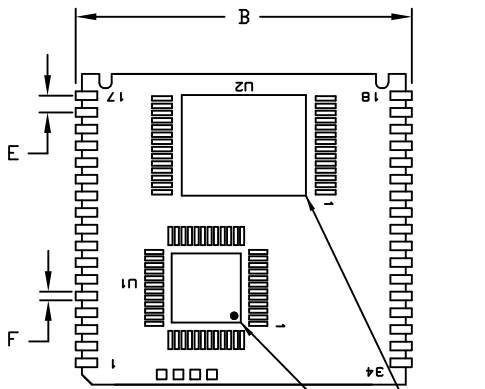
PowerCap™ Module Base



TOP VIEW



SIDE VIEW



BOTTOM VIEW


COMPONENTS AND PLACEMENT MAY VARY BY DEVICE TYPE.

REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED

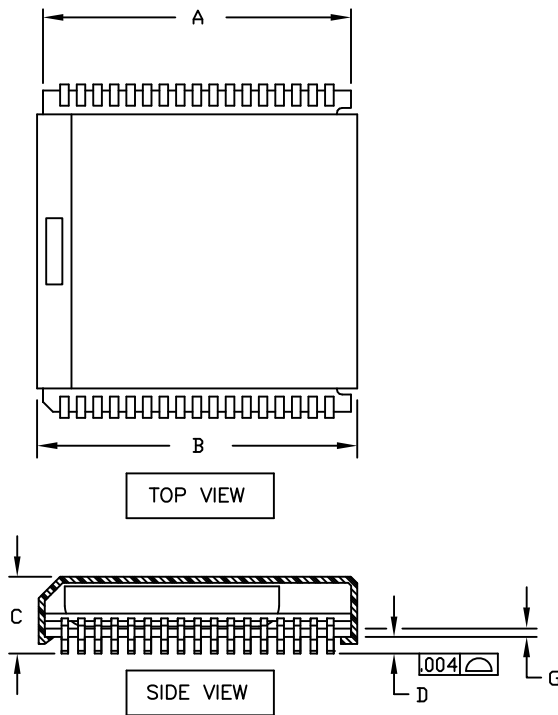
PKG DIM	INCHES		
	MIN	NOM	MAX
A	0.920	0.925	0.930
B	0.980	0.985	0.995
C	0.002	—	—
D	0.050	0.055	0.060
E	0.047	0.050	0.053
F	0.015	0.020	0.025
G	0.024	0.027	0.032

Notes:

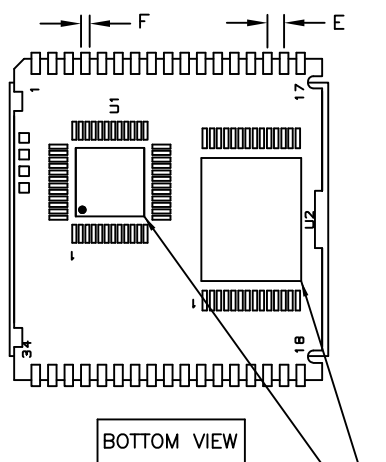
- Dallas Semiconductor recommends that PowerCap module bases experience one pass through solder reflow, oriented with the label side up ("live bug").
- Hand soldering and touch-up: Do not touch or apply the soldering iron to leads more than 3 seconds. To solder, apply flux to the pad, heat the lead frame pad, and apply solder.
- To remove the part, apply flux, heat the lead frame pad until the solder melts, then use solder wick to remove the solder.

SIGNATURE	DATE	 PowerCap™ .990 34 Pin PowerCap™ Module			
DOC. CONTROL:					
ENGR. MGR:					
MFG. ENGR:					
CHECKED BY:					
DRAWN BY: M.ZUCCO	11/04	SIZE A	FSCM NO	DWG NO. 21-0246	REV A
DIP_ModulesIC.SLDDRW		SCALE N/A	SHEET 1 OF 3		

PowerCap™ Base with DS9034PCX Attached



PKG	INCHES		
DIM	MIN	NOM	MAX
A	0.920	0.925	0.930
B	0.950	0.960	0.970
C	0.240	0.255	0.270
D	0.050	0.055	0.060
E	0.047	0.050	0.053
F	0.015	0.020	0.025
G	0.024	0.027	0.032



Notes:

1. The DS9034PCX cap contains a lithium battery. Do not exceed 80°C.
2. Remove the cap before touching up the base.
3. If the base is washed, remove the cap before washing.
4. If the base is washed, make sure it is dry before attaching the cap.



SIZE
A

FSCM NO

DWG NO.

21-0246

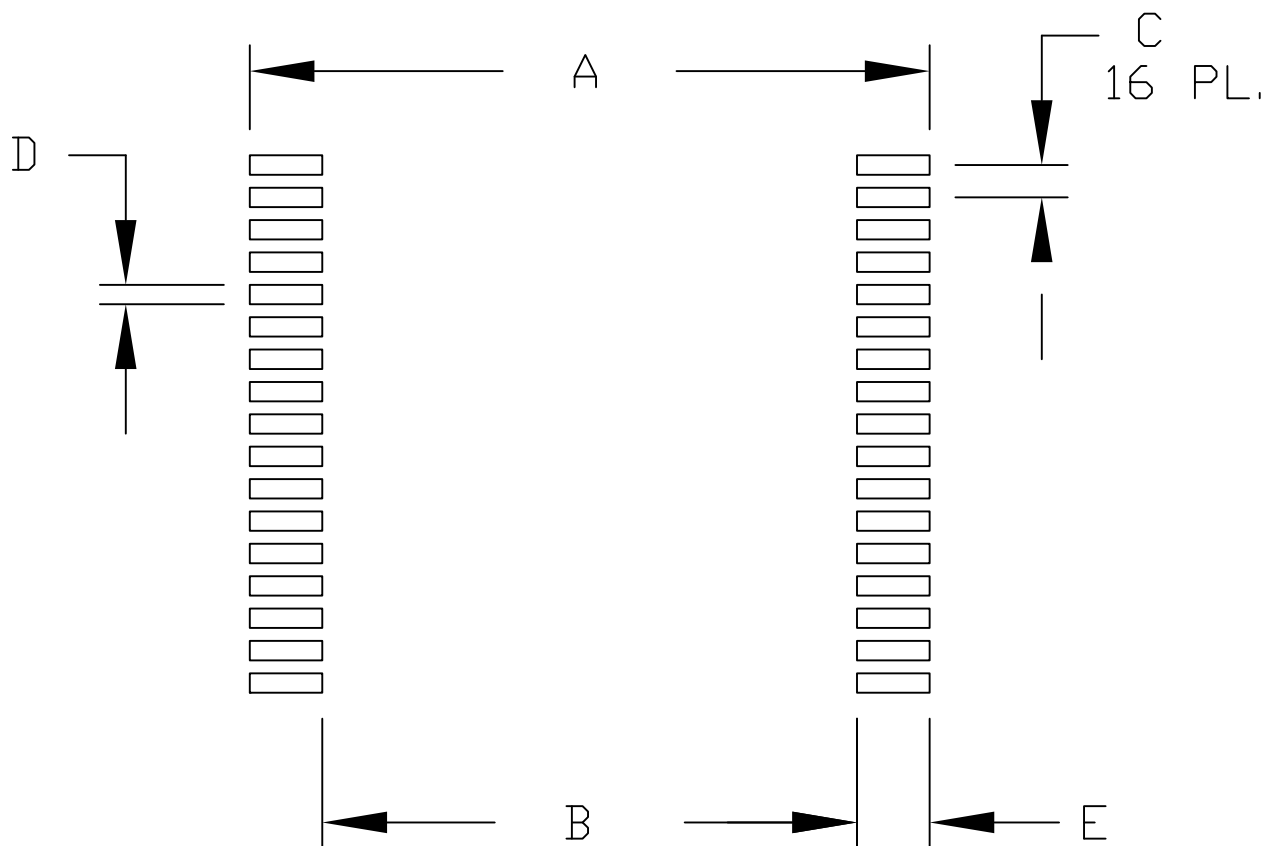
REV
A

SCALE N/A

SHEET 2 OF 3

Recommended PowerCap™ Module Land Pattern

PKG DIM	INCHES		
	MIN	NOM	MAX
A	—	1.050	—
B	—	0.826	—
C	—	0.050	—
D	—	0.030	—
E	—	0.112	—



SIZE
A

FSCM NO

DWG NO.

21-0246

REV
A

SCALE N/A

SHEET 3 OF 3